

Surface Mount

Monolithic Amplifier

50Ω, DC to 1000 MHz

NEW!

MAR-8ASM



CASE STYLE: WW107

Features

- exact footprint substitute** MAR-8SM and MSA-0886
- high gain, 31.5 dB at 100 MHz, reduces component count
- high power output, +12.5 dBm typ.
- low noise
- improved stability
- protection against power supply transients
- patent pending

Applications

- cellular
- PCN & instrumentation

Electrical Specifications @ 25°C

MODEL NO.	FREQ. (MHz)	GAIN, dB			MAXIMUM POWER, dBm	DYNAMIC RANGE		VSWR (:1) Typ.		ABSOLUTE MAXIMUM RATING*		DC POWER @ Pin 3				THERMAL RESISTANCE θjc, typ. °C/W	PRICE \$	
		Typical @ 100 MHz	Typical @ 1000 MHz	Min.		NF dB Typ.	IP3 dBm Typ.	In	Out	I (mA)	P (mW)	Current (mA)	Device Volt Min.	Typ.	Max.			Qty. (30)
MAR-8ASM	DC-1000	31.5	25	20	12.5	13	3.1	25	1.4	1.8	65	250	36	3.2	3.7	4.2	140	1.12

*Permanent damage may occur if any of these limits are exceeded.
Min. gain at 1000 MHz
Output power, NF, and IP3 at 1000 MHz.

** See Bias resistor table; resistor values are higher than MAR-8SM/MSA-0886
how to replace: increase bias resistor (Rbias) by 110 ohms
benefits: • lower device voltage, 3.7V typ.
• lower power dissipation in the MMIC
• may eliminate need for choke (RFC)

Maximum Ratings

Operating Temperature	-40°C to 85°C
Storage Temperature	-55°C to 100°C
Junction Temperature	150°C

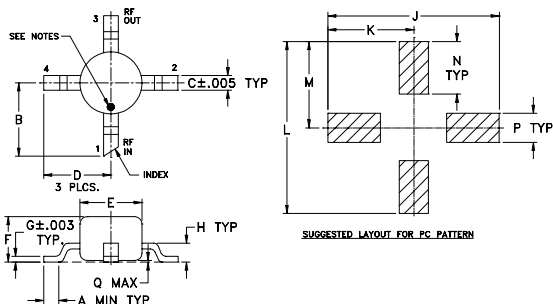
Pin Configuration

RF IN	1
RF OUT	3
DC	3
GND EXT.	2,4

Model Identification

Model	marking
MAR-8ASM	8A

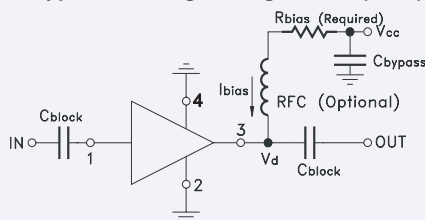
Outline Drawing



Outline Dimensions (inch/mm)

A	B	C	D	E	F	G	H	J	K	L	M	N	P	Q	wt. grams
.012	.10	.020	.092	.085	.060	.007	.026	.235	.118	.235	.118	.072	.040	.020	
.30	2.54	.51	2.34	2.16	1.52	.18	.66	5.97	3.00	5.97	3.00	1.83	1.02	0.51	.015

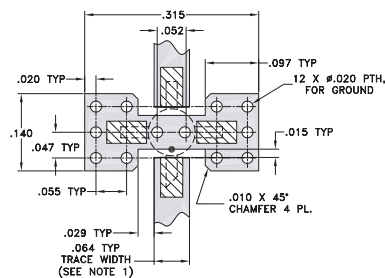
Typical Biasing Configuration (MAR)



Resistor Values

Vcc	"1%" Res.
7	88.7
8	118
9	143
10	174
11	200
12	226
13	255
14	280
15	309

Suggested PCB layout (PL-075)



NOTES:

1. TRACE WIDTH IS SHOWN FOR ROGERS RO4350 WITH DIELECTRIC THICKNESS 0.030" ± 0.002", COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. IF YOUR PCB DESIGN RULES ALLOW, GROUND VIAS SHOULD BE PLACED UNDER THE LAND PATTERN FOR BETTER RF PERFORMANCE. OTHERWISE GROUND VIAS SHOULD BE PLACED AS CLOSE TO LAND PATTERN AS POSSIBLE.

- DENOTES PCB COPPER LAYOUT
- ▨ DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

REV. A
M91596
ED-9366/12
MAR-8ASM
MM/FL/CP/AM
040323
page 1 of 4



INTERNET <http://www.minicircuits.com>

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661

Distribution Centers NORTH AMERICA 800-654-7949 • 417-335-5935 • Fax 417-335-5945 • EUROPE 44-1252-832600 • Fax 44-1252-837010

ISO 9001 CERTIFIED

